

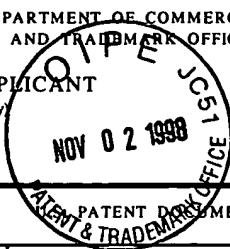
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LIST OF ART CITED BY APPLICANT

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3729

*Examiner Initial	Document Number	Date	Name	Class	Subclass	Filing Date If Appropriate
AA						
AB						
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FOREIGN PATENT DOCUMENTS							
	Document Number	Date	Country	Class	Subclass	Translation	
						Yes	No
AL							
AM							
AN							
AO							
AP							

OTHER REFERENCES (including Author, Title, Date, Pertinent Pages, Etc.)

W	AR	Kasulke, P., et al., "Solder Ball Bumper (SBB) - A Flexible Equipment for FC, CSP, BGA and Printed Circuit Boards", "An Innovative Solution for Solder Application Solder Ball Bumper (SBB)", Pac Tech Packaging Technologies GmbH and
		Fraunhofer IZM, pp. 1-8.
	AS	
	AT	

EXAMINER

A. Dastu Tugbong

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12/3/99

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